

PCN# 20190502000.1
Transfer of select LDMOS devices from GFAB to FFAB Wafer Fab site
Change Notification / Sample Request

Date: May 03, 2019
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20190502000.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMD18245T/NOPB	null
LMD18200T/NOPB	null
LMD18201T/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN Number: 20190502000.1 **PCN Date:** May 3, 2019

Title: Transfer of select LMDMOS devices from GFAB to FFAB Wafer Fab site

Customer Contact: [PCN Manager](#) **Dept:** Quality Services

Proposed 1st Ship Date: Aug 3, 2019 **Estimated Sample Availability:** Date provided at sample request.

Change Type:

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

PCN Details

Description of Change:

This change notification is to announce the transfer of select LMDMOS devices from GFAB to the FFAB (FR-BIP-1) Wafer Fab site for the selected devices listed in the "Product Affected" section.

Current Fab Site			New Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
GFAB6	LMDMOS	150 mm	FFAB	LMDMOS	200 mm
GFAB8	LMDMOS	200 mm	FFAB	LMDMOS	200 mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Greenock, Scotland (GFAB) Wafer Fab site closure

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock

New Fab Site

Chip Site	Chip Site Origin (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	TID	DEU	Freising

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:
 MSL '2 / 260C / 1 YEAR SEAL DT
 MSL 1 / 235C / UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected Group:

LM2640MTC-ADJ/NOPB	LMD18200T/LF14	LMD18201T	LMD18245T
LMD18200T	LMD18200T/NOPB	LMD18201T/NOPB	LMD18245T/NOPB

Qualification Report

Approve Date 24-Apr-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LMD18245T/NOPB	QBS Device: LM2675M-5.0/NOPB
AC	Autoclave 121C	96 Hours	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	3/90/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-
HBM	ESD - HBM	2000 V	3/9/0	-
CDM	ESD - CDM	250 V	3/9/0	-
HTOL	Life Test, 125C	1000 HOURS	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 HOURS	-	3/231/0
LU	Latch-up	(per JESD78)	3/18/0	3/18/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass
MQ	Manufacturability (Wafer Fab)	(per mfg. Site specification)	Pass	Pass
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0
WLR	Wafer level Reliability	(Per Site Specification)	-	Pass

- Qual Devices qualified at LEVEL1-260CG: LMD18245T/NOPB

- QBS: Qual By Similarity

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com